PLASTIC-MOLDED-TYPE HOLLOW SEMICONDUCTOR DEVICE AND PROCESS FOR MANUFACTURING SAME

ABSTRACT OF THE DISCLOSURE

A plastic-molded-type hollow semiccnductor device includes a base and a cover, which are joined together by a thermosetting resin bonding material that is applied to the entire edge surfaces of the cover as well as bonding surfaces of the base and the cover. The thermosetting resin bonding material is applied after placing the cover on the base and simultaneously pre-heating them, whereby the inner gas trapped between the base and the cover is prevented from expanding, so that the generation of through-holes is eliminated, thereby making it possible to obtain a semiconductor device which provides a high level of handling property and reliability.

Figure 1